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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Tai-Chong CHAI et al.

Serial Number:

Filed: 2/7/00

LEAD FRAME FOR AN INTEGRATED
CIRCUIT CHIP (Small Window)

) Patent Group Art Unit:

) Examiner:



* * * * *

TRANSMITTAL OF CERTIFIED PRIORITY DOCUMENTS

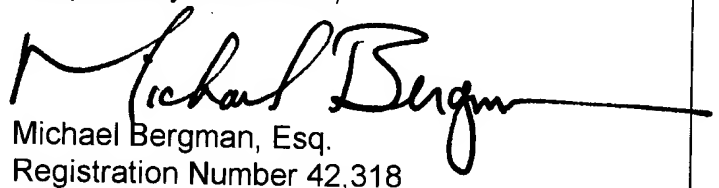
Washington, DC
7 February, 2000

Honorable Commissioner of Patents and Trademarks
Washington, DC 20231

Sir:

The applicant hereby completes the claim for priority of the corresponding patent application number 9900055-6, filed 9 February, 1999 in Singapore, by submitting herewith a certified copy thereof in accordance with 35 U.S.C. § 119 and 37 CFR § 1.55(b).

Respectfully Submitted,


Michael Bergman, Esq.
Registration Number 42,318

WATSON COLE GRINDLE WATSON, P.L.L.C.
10th Floor, 1400 K Street
Washington, DC 20005-2477
tel: (202) 628-3600
fax: (202) 628-3650

**REGISTRY OF PATENTS
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This is to certify that the annexed is a true copy of the following Singapore patent application as filed in this Registry.

Date of Filing : 09 FEBRUARY 1999
Application number : 9900055-6
Applicant(s) : INSTITUTE OF MICROELECTRONICS
Title of Invention : LEAD FRAME FOR AN INTERGRATED
CIRCUIT CHIP (small window)




Jasmine Ong (Miss)
Assistant Registrar
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SINGAPORE

10TH SEPTEMBER 1999

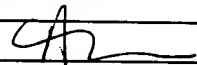
2117/99

The Registrar of Patents
Registry of Patents

REQUEST FOR THE GRANT OF A PATENT

THE GRANT OF A PATENT IS REQUESTED BY THE UNDERSIGNED ON THE BASIS OF
THE PRESENT APPLICATION.

I. Title of Invention	LEAD FRAME FOR AN INTEGRATED CIRCUIT CHIP (small window)			
II. Applicant(s) (See note 2)	(a) Name	INSTITUTE OF MICROELECTRONICS		
	Body Description/ Residency	A company limited by guarantee		
	Street Name & Number	11 Science Park Road Singapore Science Park II		
	City			
	State			
	Country	Singapore 117685		
	(b) Name			
	Body Description/ Residency			
	Street Name & Number			
	City			
	State			
	Country			
	(c) Name			
	Body Description/ Residency			
	Street Name & Number			
	City			
	State			
	Country			
III. Declaration of Priority (see note 3)	Country/ Country Designated		File No.	
	Filing Date			
	Country/ Country Designated		File No.	
	Filing Date			
	Country/ Country Designated		File No.	
	Filing Date			

IV. Inventors <i>(see note 4)</i> (a) the applicant(s) is/are the sole/joint inventor(s) (b) A statement on Patents Form 8 is/will be furnished.	<div style="display: flex; justify-content: space-around; align-items: center;"> <div style="text-align: center;"> <input type="checkbox"/> Yes </div> <div style="text-align: center;"> <input checked="" type="checkbox"/> No </div> </div> <div style="display: flex; justify-content: space-around; align-items: center;"> <div style="text-align: center;"> <input checked="" type="checkbox"/> Yes </div> <div style="text-align: center;"> <input type="checkbox"/> No </div> </div>			
V. Name of Agent (if any) <i>(See note 5)</i>	ALLEN & GLEDHILL			
VI. Address for Service	Block/Hse No.	36	Level No	18
	Unit No./PO Box	01	Postal Code	068877
	Street Name	ROBINSON ROAD		
	Building Name	CITY HOUSE		
VII. Claiming an earlier filing date under Section 20(3), 26(6) or 47(4). <i>(See note 7)</i>	Application No.			
	Filing Date			
VII. Invention has been displayed at an International Exhibition <i>(See note 8)</i>	<div style="display: flex; justify-content: space-around; align-items: center;"> <div style="text-align: center;"> <input type="checkbox"/> Yes </div> <div style="text-align: center;"> <input checked="" type="checkbox"/> No </div> </div>			
IX. Section 114 requirements <i>(See note 9)</i>	The invention relates to and/or used a micro-organism deposited for the purpose of disclosure in accordance with Section 114 with a depository authority under the Budapest Treaty <div style="display: flex; justify-content: space-around; align-items: center;"> <div style="text-align: center;"> <input type="checkbox"/> Yes </div> <div style="text-align: center;"> <input checked="" type="checkbox"/> No </div> </div>			
XII. Check List (To be filled in by applicant or agent)	A. The application contains the following number of sheet(s):-			
	1. Request.	3	sheets	
	2. Description	7	sheets	
	3. Claim(s).	3	sheets	
	4. Drawing(s).	4	sheets	
	5. Abstract	1	sheets	
	B. The application as filed is accompanied by:-			
	1. Priority document.			
	2. Translation of priority document.			
	3. Statement of Inventorship & right to grant.			
	4. International Exhibition certificate			
XIII. Signatures(s) <i>(See note 10)</i>	Applicant (a)			
	Date	9 February 1999		
	Applicant (b)			
	Date			
	Applicant (c)			
	Date			

NOTES:

1. This form when completed, should be brought or sent to the Registry of Patents together with the prescribed fee and 3 copies of the description of the invention, and of any drawings.
2. Enter the name and address of each applicant in the spaces provided at paragraph II. Names of individuals should be indicated in full and the surname or family name should be underline. The names of all partners in a firm must be given in full. The place of residence of each individual should also be furnished in the space provided. Bodies corporate should be designated by their corporate name and country of incorporation and, where appropriate, the state of incorporation within that country should be entered where provided. Where more than three applicants are to be named, the names and address of the fourth and any further applicants should be given on a separate sheet attached to this Form together with the signature of each of these further applicants.
3. The declaration of priority at paragraph III should state the date of the previous filing, the country in which it was made, and indicate the file number, if available. Where the application relied upon in an International Application or a regional patent application e.g. European patent application, one of the countries designated in that application [being one falling under the Patents (Convention Countries) Order] should be identified and the name of that country should be entered in the space provided.
4. Where the applicant or applicants is/are the sole inventor or the joint inventors, paragraph IV should be completed by marking the "YES" Box in the declaration (a) and the "NO" Box in the alternative statement (b). Where this is not the case, the "NO" Box in declaration (a) should be marked and a statement will be required to be filed on Patents Form 8.
5. If the applicant has appointed an agent to act on his behalf, the agent's name should be indicated in the spaces available at paragraphs V.
6. An address for service in Singapore to which all documents may be sent must be stated at paragraph VI. It is recommended that a telephone number be provided if an agent is not appointed.
7. When an application is made by virtue of section 20(3), 26(6) or 47(4), the appropriate section should be identified at paragraph VII and the number of the earlier application or any patent granted thereon identified.
8. Where the applicant wishes an earlier disclosure of the invention by him at an International Exhibition to be disregarded in accordance with section 14(4)(c), then the "YES" box at paragraph VIII should be marked. Otherwise the "NO" box should be marked.
9. Where in disclosing the invention the application refers to one or more micro-organisms deposited with a depositary authority under the Budapest Treaty, then the "YES" box at paragraph IX should be marked. Otherwise, the "NO" box should be marked.
10. Attention is drawn to rules 90 and 105 of the Patent Rules 1995. Where there are more than three applicants, see also Note 2 above.
11. Applicants resident in Singapore are reminded that if the Registry of Patents considers that an application contains information the publication of which might be prejudicial to the defence of Singapore or the safety of the public, it may prohibit or restrict its publication or communication. Any person resident in Singapore and wishing to apply for patent protection in other countries must first obtain permission from the Singapore Registry of Patents unless they have already applied for a patent for the same invention in Singapore. In the latter case, no application should be made overseas until at least two months after the application has been filed in Singapore.

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Application Filing Date : / /
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LEAD FRAME FOR AN INTEGRATED CIRCUIT CHIP
(small window)

BACKGROUND OF THE INVENTION

5 This invention relates to packaging for a semiconductor device, and more particularly to a crack and delamination inhibiting lead frame for a semiconductor integrated circuit with a small window.

10 Conventional plastic semiconductor packages suffer from a failure mode referred to as "popcorn cracking." This failure mode occurs in packages that are exposed to ambient moisture and are then heated to high temperatures, typically during reflow soldering.

15 The problem apparently arises because plastic IC packages have a tendency to absorb moisture from the environment. The moisture diffuses into the encapsulant material and other materials such as the chip attach. During the solder reflow process, thermal vapor stresses developed at the chip attach/chip-pad interface or the encapsulant material/chip-pad interface cause delamination to occur, especially at areas of high interfacial stress.

20 A conventional full pad design is shown in figures 6, 6A and 6B where a chip or die 10 has its lower side 12 secured to a chip pad 14 by a chip attach material 16. The chip attach 16 forms a fillet 18 between the side wall 20 of the chip 10 and the upper surface 22 of the chip pad 14 in an outer region known as the shoulder 24. The pad 14 and attached chip 10 are thereafter encapsulated in an encapsulant material 26, for example epoxy forming a package 30 in a known manner. In Fig. 6A, the package 30 is fabricated on a metal leadframe 31. The package 30 includes wire bonds 37.

25 The failure process appears to begin with delamination or cracking of the bond between the chip and the chip-pad. This delamination may be caused by differential expansion due to the differing coefficients of thermal expansion of adjacent materials within the package. Delamination 38 of the chip 10 from the chip pad 14 can occur

when the interfacial stresses exceed the interfacial strength. Once delamination begins, it can propagate. The expanding void created by this delamination is invaded by water vapor, previously absorbed into the encapsulant material, and driven from the encapsulant by the rise in temperature. If the delamination covers a large area, the resulting long moment across which expansive water vapor forces act allows those forces to overcome the cohesive forces within the encapsulant material. In particular, delamination 38 often starts near the corner 32 of the chip 10, where the chip 10 meets the shoulder 24. In the case of the full pad design shown, delamination can rapidly propagate over the entire pad area. This can cause the package 30 to crack from the outer edge 34 of the chip pad 14 where the cohesive strength of the encapsulant material 26 is exceeded. The resulting crack may propagate through the encapsulant material 26 to the outer surface 36 of the package 30. In a like manner, delamination of the chip pad 14 from the encapsulant material 26 can also act as a crack source resulting in a popcorn failure.

These problems necessitate storage of components in humidity controlled environments prior to reflow soldering. Such required storage procedures represent additional cost and uncertainty in product quality.

SUMMARY OF THE INVENTION

The invention is based upon the discovery that a lead frame for a crack resistant integrated circuit package has an apertured frame, of reduced size, smaller than the integrated circuit. In a package utilizing the lead frame, the integrated circuit or chip is attached to the upper surface of the frame, and encapsulant material encloses and surrounds the frame and the chip. The encapsulant material bonds to a majority of the surface area of the chip and hardens to complete the package.

The invention provides a lead frame that reduces the initial adhesive failure, or delamination, that can occur during high temperature exposure that results in popcorn cracking. In an exemplary embodiment, this is achieved by reducing or minimizing the

size of the attachment surface of the frame to the chip. The minimal attachment surface limits the propagation of cracks and increases the available bonding surface area below the chip and encapsulant.

BRIEF DESCRIPTION OF THE DRAWINGS

5 The objects and advantages of the present invention will become apparent by reference to the following description and accompanying drawings wherein:

FIG. 1 is a bottom plan view of a Small-Window-Chip-Support (SWCS) lead frame according to an exemplary embodiment of the invention;

10 FIG. 1A is a cross section of the SWCS lead frame of FIG. 1, taken along line 1A-1A;

FIG. 2 is a plan view of a SWCS design employing grounding ring;

FIG. 2A is a cross section of the SWCS of FIG. 2, taken along line 2A-2A thereof;

FIG. 3 is a plan view of a SWCS design employing a grounding lead;

FIG. 3A is a cross section of the SWCS of FIG. 3, taken along line 3A-3A thereof;

FIG. 4 illustrates a small window arrangement with a round apertured frame;

FIG. 5 illustrates a small window arrangement with enlarged support members;

FIG. 6 is a fragmentary plan view of a conventional integrated circuit package formed on a thin metal leadframe and employing a conventional full size chip pad;

FIG. 6A is a fragmentary side elevation of the lead frame of FIG. 6; and

FIG. 6B is a fragmentary perspective view of the lead frame of FIG. 6.

DETAILED DESCRIPTION OF THE INVENTION.

FIGs.1 and 1A illustrate an exemplary embodiment of a portion of an integrated circuit package incorporating a small window chip support lead frame 42 for an integrated circuit chip or die 44 according to the invention. The chip 44 has a respective top 46, and bottom 48. It also has sides 50 and side edges 55. The lead frame 42 reduces or eliminates popcorn cracking failures during periods of high temperature processing; for example, during reflow soldering.

In the present embodiment, the lead frame 42 includes four interconnected coplanar sidebars 52 defining an aperture or window 54. In this embodiment, each sidebar 52 also has opposite ends 56 and respective inner sides 62 and outer sides 64. The outer sides 64 define a chip supporting zone 43. It is characteristic of the invention that the chip supporting zone 43 has a periphery lying generally within the periphery of the chip. In most instances, the entire lead frame 42 is etched or stamped from a thin conductive metal sheet, for example copper sheet. Typically, the thickness of the metal sheet is in the range from about 4 mils to about 8 mils. Other materials and thicknesses may be appropriate for various applications.

The sidebars 52 are joined at respective ends 56 to define the aperture 54. A chip contacting surface comprising the upper surface 63 of each side bar 52 is disposed in confronting relation with the bottom 48 of the chip 44. As shown, the chip 44 is secured to the upper surface 63 of each side bar 52 by a chip attach material 66. The

sides 50 of chip 44 are then located in spaced relation with the outer side 64 of the side bars 52 as shown.

In a known manner wire bonds 69 are connected to the top 46 of the chip 44 as schematically shown. Encapsulation material 68, shown in dotted line, is molded around the frame 42 and chip 44 as shown. The encapsulation material 68 forms a bond with the frame 42 and also bonds to the top 46, bottom 48 and sides 50 of the chip 44. As can be appreciated the encapsulating material 68 is molded through and around the frame 42 to form a firm and robust bond with the bottom 48 of the chip 44 through the aperture 54.

As noted above, the chip 44 is secured to a portion of the top surface 63 of the side bars 52 by the chip attach material, or adhesive, 66. The arrangement of chip and sidebars, discussed above, whereby the periphery of the chip supporting zone is within the periphery of the chip insures that the die attach material contacts the bottom of the chip remotely from the high-stress chip corners 41. As best shown in FIG. 1, the chip 44 is supported on the frame 42 with its sides 50 generally parallel to and spaced beyond the side bars 52, exposing available inner 98 and outer 99 bonding areas on the bottom of the chip. This allows the encapsulation material to bond to both areas on the bottom of the chip and around the frame 42 to provide a strong bond.

The upper surface 63 of each side bar 52 provides a relatively small contact area with the chip. Such a small total bonding area minimizes possible delamination span, and the consequent probability of popcorn cracking. A window format, as compared with less integrated alternatives, is used to enhance mechanical stability during assembly prior to mold encapsulation.

As can be seen in FIG. 1 and FIG. 1A, the apertured frame 42 is surrounded by different materials including the encapsulating material 68, which thus forms materials discontinuities at various boundaries in the package 40. Accordingly, cracks originating at the interface in the chip attach material 66 between the chip 44 and the frame 42, tend to stop at the boundary where the materials are discontinuous.

Side bars 52 have a length l . Importantly, the side bar length l is at the outer side 64 generally less than the corresponding length L of the chip along the side edge 55 to thereby eliminate the chip-pad shoulder 24 and the chip-pad attach fillet 18 of the prior art.

As can be seen in FIG. 1, although the frame 42 provides a relatively small contact area for the chip 44, it is sufficient to secure the chip 44 in place while the assembly is being encapsulated. Significantly, the lead frame exhibits no shoulder region, and all die attach interfaces are remote from chip corners. Consequently the weaker materials, more prone to delamination, are not found in the high stress corner and shoulder regions. The resulting package 40 is robust, ultimately providing relatively high strength bonds between the chip and frame upon encapsulation. The permanent bond formed between the chip 44 and the encapsulation 68 has a large surface area relative to the chip attach bond. Failure of the chip attach after encapsulation thus does not adversely affect package integrity because of the superior strength of the encapsulating material.

The lead frame also includes support members 80 which extend from the corners 82 of the frame 42. The support members serve to support the sidebars 52 within the mold during application and hardening of the encapsulant material.

Various other embodiments of the invention provide advantages complimentary to those already described.

FIGs. 2 and 2A illustrate a ground ring 81 which surrounds the chip 44 and is in spaced relation therewith. As shown, the ground ring 81 is electrically conductive and forms a ground plane for the chip 44.

FIGs. 3 and 3A illustrates an arrangement with a ground lead 86 having a proximal end 88 connected to the frame 42 and having a free end 90 for ground wire bonding if needed.

FIG. 4 illustrates a small window arrangement with a round apertured frame. In this embodiment, the function of the sidebars 52, as illustrated in FIG. 1 is performed

by a circular or annular member 100 with a circumferential edge 101 and upper surface 102 fixed in bearing contact with the bottom 104 of the chip 106, and disposed within the chip edge 108.

FIG. 5 illustrates a small window arrangement with enlarged support members 120.

This arrangement presents additional surface area to the bottom of the chip 122, and provides additional stability during the molding of encapsulant material, and possibly thermal benefits in operation.

FIG. 5 further illustrates an aperture traversing member 125. In this embodiment, this member serves to divide the aperture into two smaller apertures 126 and 127.

It will be appreciated by persons skilled in the art that numerous variations and modifications may be made to the invention as shown in the specific embodiments without departing from the spirit or scope of the invention as broadly described. The present embodiments are therefore to be considered in all respects illustrative and not restrictive.

We claim:

1. A lead frame, for an integrated circuit chip having a frame engaging bottom surface, comprising:
 - a plurality of sidebars,
 - each of said sidebars having an inner side and an outer side,
 - said inner sides defining an aperture,
 - said outer sides defining a chip-support zone,
 - said zone being smaller in each dimension than the corresponding dimension of the chip,
 - each sidebar having an upper chip-supporting surface for engaging the bottom surface of the chip.
2. The lead frame of claim 1, wherein said chip-supporting surface engages the bottom of the chip at a location remote from the high stress regions associated with the corners of the chip to minimize the risk of delamination.
3. The lead frame of claim 1 wherein at least one of said sidebars is generally rectilinear.
4. The lead frame of claim 1 wherein at least one of said sidebars is generally curvilinear.
5. The lead frame of claim 1, further comprising: one or more aperture traversing members, said members serving to divide said aperture into a plurality of smaller apertures.
6. The lead frame of claim 1, further comprising:
 - a plurality of support members having proximal and distal ends, each support

member being connected to at least one sidebar by said respective proximal end.

7. The lead frame of claim 1 wherein said sidebars further comprise: opposite ends, said opposite ends intersecting to define corners.

8. The lead frame of claim 7, further comprising:
a plurality of support members having proximal and distal ends, each support member being connected to at least one sidebar by said respective proximal end.

9. The lead frame of claim 8, wherein each of said connections between each support member and the at least one sidebar is in the vicinity of said respective corner.

10. The lead frame of claim 1, further comprising a ground ring surrounding the chip in spaced relation thereabout.

11. The lead frame of claim 1, further comprising:
a plurality of leads, said leads being electrically isolated from said sidebars and disposed outside of said aperture, each of said leads having a proximal end and a distal end, said proximal end being proximate to said sidebars.

12. A lead frame for connecting and supporting an integrated circuit chip having an outer chip edge, comprising:

an apertured frame including interconnected side bars defining an outer frame edge, said frame edge being disposed within the outer chip edge, thus having no shoulder, and therefore minimizing fillet formation, and having a contact surface for securing the chip thereto.

13. A lead frame for an integrated circuit chip having a frame-engaging bottom surface, comprising:

a plurality of sidebars, each of said sidebars having an inner side and an outer side, said sidebars defining an aperture, said frame being sized to be accommodated entirely within corresponding outer edges of the side chip, each side bar having an upper chip-supporting surface for engaging the lower surface of the chip.

14. A lead frame for an integrated circuit chip having a frame engaging bottom surface comprising:

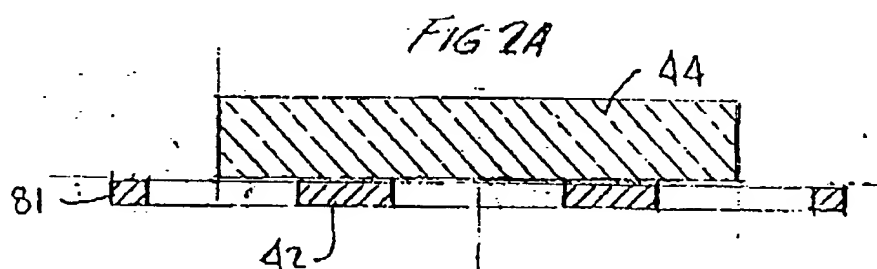
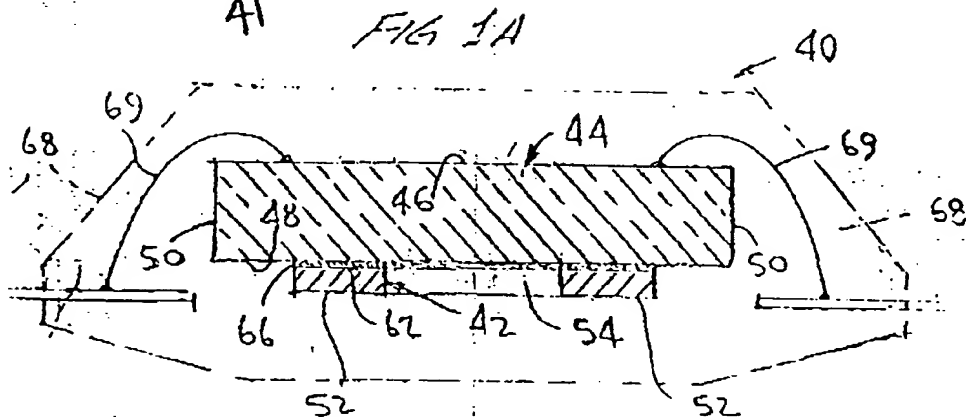
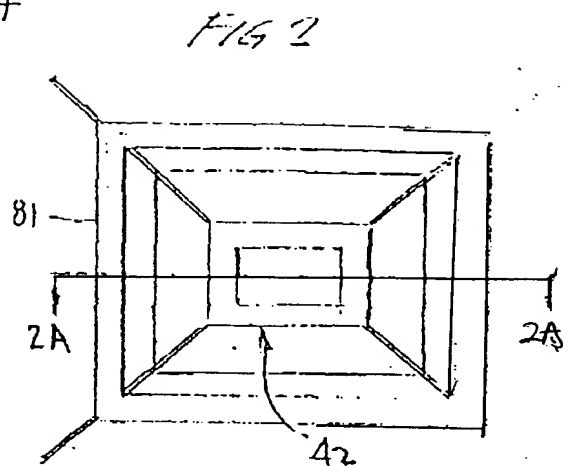
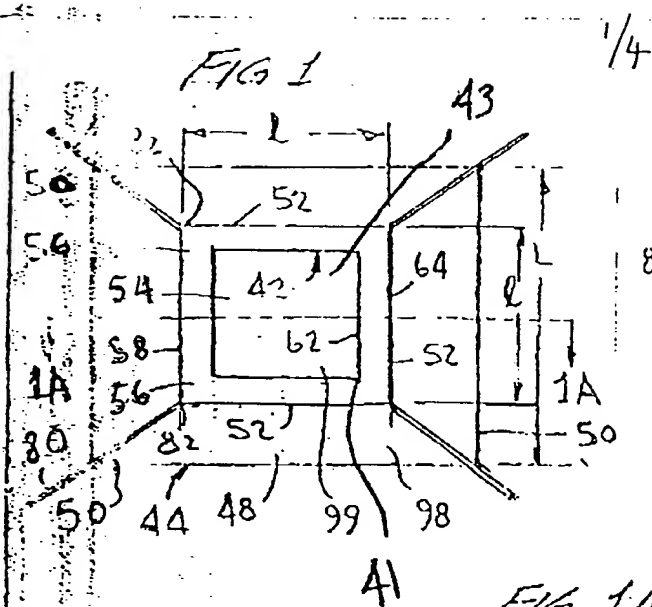
an apertured frame said frame being generally circular and defining a circumferential edge and having a contact surface for securing the chip thereto, said frame edge being disposed within the outer chip edge for minimizing fillet formation.

LEAD FRAME FOR AN INTEGRATED CIRCUIT CHIP
(small window)

ABSTRACT

A lead-frame for connecting and supporting an integrated circuit having an apertured frame with dimensions smaller than the corresponding dimensions of the chip so that chip-pad shoulder can be eliminated and the chip attach fillet is made remote from the chip corner.

Figure 1



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FIG. 3

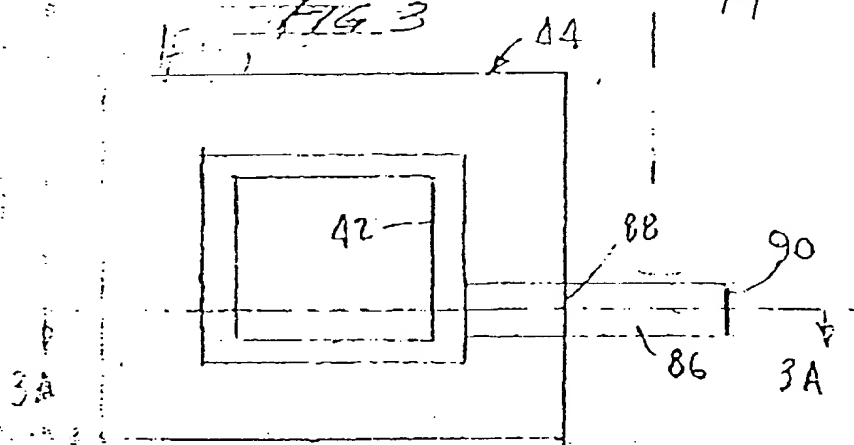


FIG. 3A

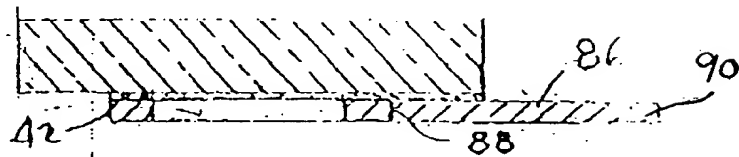
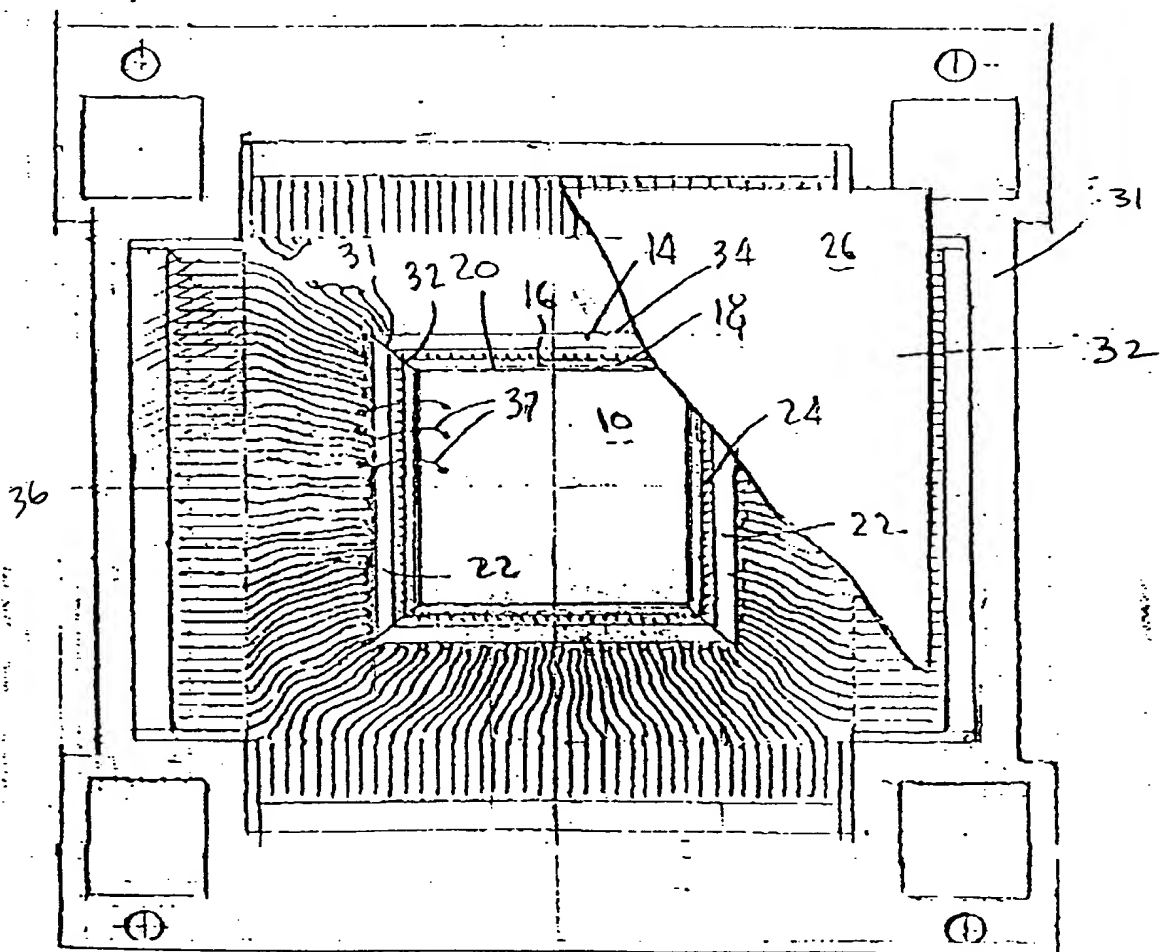


FIG. 6

30



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FIG. 4

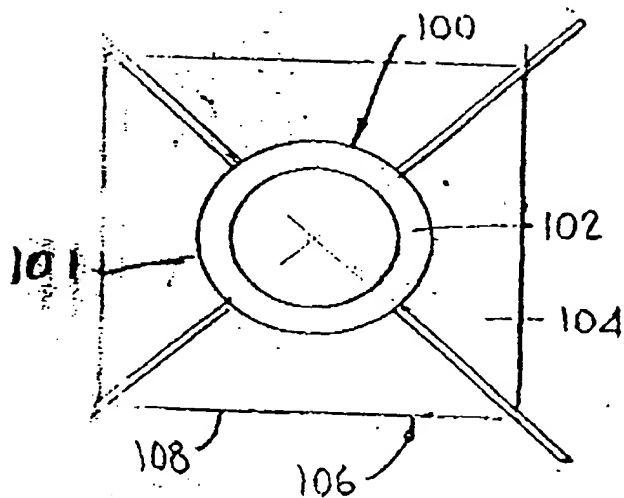


FIG. 5

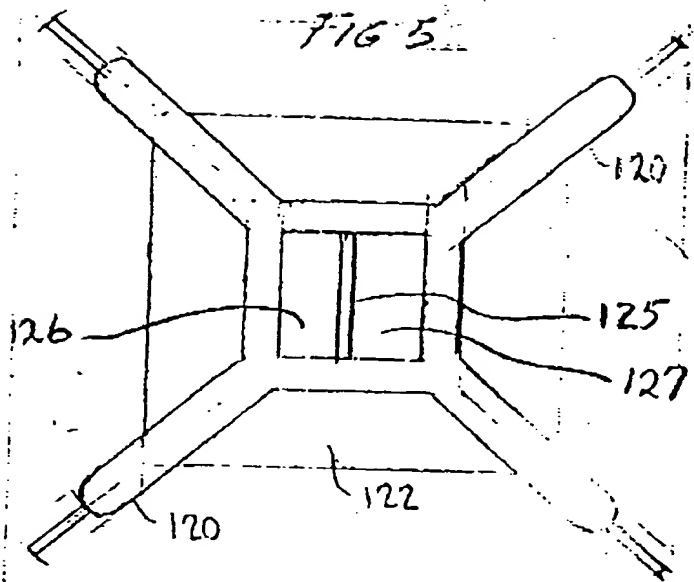


FIG 6A

